

AMENDMENTS TO THE CLAIMS

A listing of the claims is provided for the Examiner's convenience.

1. (Previously Presented) A method for producing an electrical device made up by a first object for bonding including a first electrode and a second object for bonding including a second electrode to be connected to said first electrode, by bonding said first object for bonding and said second object for bonding to each other, comprising the steps of
 - arranging an adhesive, mainly containing a thermosetting resin and a silane coupling agent as a first curing agent, at least on said first electrode, to form an adhesive layer, wherein electrically conductive particles are added to said adhesive from the outset;
 - arranging a second curing agent, reacted with said first curing agent by heating to polymerize said thermosetting resin, at least on said second electrode, to form a layer of the second curing agent, said second curing agent being mainly composed of one or both of an aluminum chelate and an aluminum alcoholate;
 - positioning said first and second electrodes in register with each other;
 - tightly contacting said adhesive on said first object for bonding with said second curing agent on said second object for bonding; and
 - thrusting and heating said first and second objects against each other for bonding to develop a cation by reaction of said silane coupling agent as a main component of said first curing agent and one or both of said aluminum chelate and said aluminum alcoholate of the second curing agent and for interconnecting said first and second electrodes through said electrically conductive particles and allowing said thermosetting resin to be cationically polymerized by heating.
2. (Cancelled)
3. (Cancelled)
4. (Previously Presented) The method for producing an electrical device according to claim 1 wherein said aluminum chelate is one of ethyl acetoacetate aluminum diisopropylate, alkyl

acetoacetate aluminum diisopropylate and aluminum monoacetyl acetate bis ethylacetoacetate.

5. (Previously Presented) The method for producing an electrical device according to claim 1 wherein a compound represented by the following formula:



is used as said silane coupling agent, wherein at least one of the substituents X¹ to X⁴ is an alkoxy group and at least one of the substituents different from the alkoxy group includes an epoxy ring.

6. (Cancelled)
7. (Previously Presented) The method of producing an electrical device according to claim 1 wherein said thermosetting resin forming said adhesive layer is an epoxy resin and wherein said second curing agent layer further contains an epoxy resin.
8. (Previously Presented) The method of producing an electrical device according to claim 1 wherein said second curing layer is formed on said second electrode by spraying said second curing agent liquid at ambient temperature or a liquid dispersion containing said second curing agent dispersed therein.
9. (Cancelled)